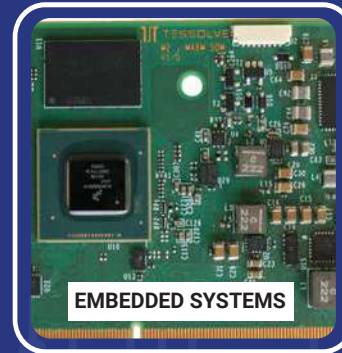
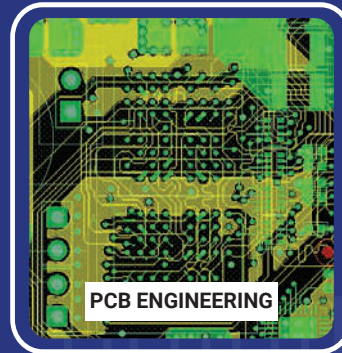
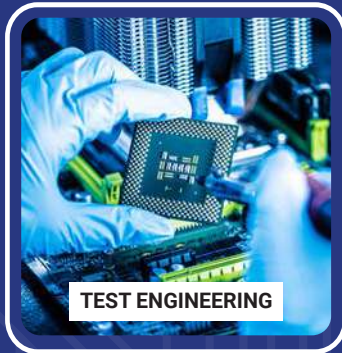
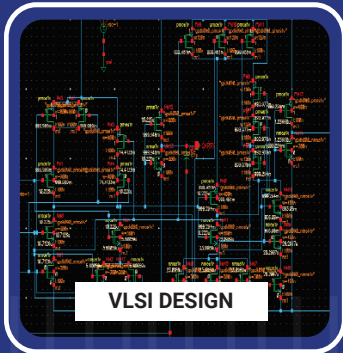


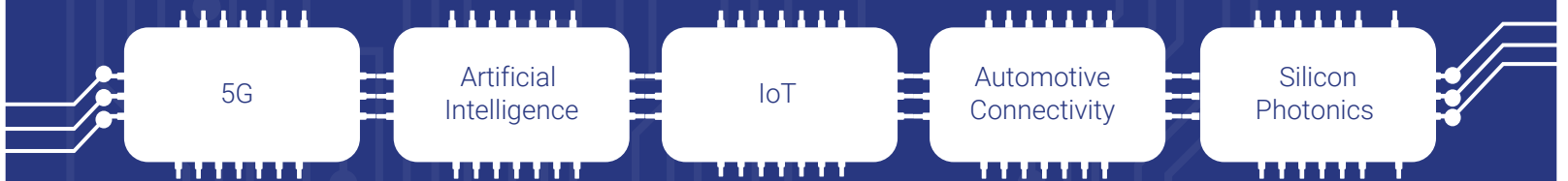
# TESSOLVE

A HERO ELECTRONIX VENTURE



**END TO END SOLUTION PROVIDER IN SEMICONDUCTOR VALUE CHAIN**  
Delivering excellence in engineering

## Key Technologies



## Market Sectors



**Committed To Your Success**



Advanced Design



Capable Partners



Empowered Customers



## VLSI Design

- ▶ Rich design experience includes – Analog, Digital & Mixed signal IPs and SoC Solutions – Spec to GDSII sign-off
- ▶ Circuit Design, Layout Design, RTL Design, DV, DFT, PD, FPGA Emulation, Verification IPs (VIP) solution, AMS design & verification
- ▶ Expertise in process nodes from 0.35um down to most advanced 7nm technology
- ▶ Executing Turnkey Projects – Ownership from Spec to GDS to Silicon



## Test Engineering

- ▶ Test Strategy & Planning
- ▶ Test Hardware Design, Test Program Development & Characterization
- ▶ Test Time Reduction, Yield Optimization, Platform Conversions, and Multisite Test - solutions that enable a seamless transition from development to production
- ▶ Multi ATE Platforms Expertise (over 30+ ATE Platforms)
- ▶ State of the art Test Floor equipped with ATE testers Advantest, Teradyne, NI etc and Rack & Stack Bench Equipment
- ▶ Device Expertise – RF, Digital, Sensors, Mixed Signal, Analog
- ▶ Product Engineering - Advanced product engineering solutions – right from R&D to end of product life



## PCB Engineering & Turnkey Manufacturing

- ▶ Multi Platform EDA Tools (Cadence, Mentor, Altium...)
- ▶ Design and delivery of ATE, Systems, Burn-in Board (BIB) and Evaluation boards
- ▶ PCB Design HDI, Blind/Buried, Flex, RF, Metal Core/Clad, High-Speed DDRx etc.
- ▶ PCB Design Simulations (SI, PI, TA, LPDDR etc.)
- ▶ Package Design ( Wire Bond, Flip Chip, SIP, WLCP)
- ▶ Mechanical Engineering
- ▶ Inhouse PCB Fab







## Reliability & FA Services

- **Reliability Services**
  - ▶ Device Qualification
  - ▶ ESD, Latch up, Burn In (HTOL, ELFR), Package Qual (HAST, HTSL, TC, TCT, THB, PTC...)
- **Failure Analysis Services**
  - ▶ VLSI Circuit Edit using 9500 FIB (5nm beam); De-Capsulation (Cu protect jet-etch); Optical Microscopy & Measurement (Nikon Iv150), X-Ray, X-Section analysis of PCB & DIE etc.



## Embedded Systems/ Products/Services

- ▶ End to end product development services from Custom Design to Manufacturing
- ▶ Linux & Android Software Development Expertise
- ▶ System Design expertise with Digital, Analog, Mixed Signal & RF design capabilities
- ▶ FPGA based system design from "RTL coding to board level Validation"
- ▶ High-end video, audio and connected multimedia embedded system
- ▶ MAGIK-2 modules based on the SMARC/Q7 standard
- ▶ Embedded Services: Linux /Android Device Drivers / Middleware/ Post Silicon Validation Activities

## Together With Our Solution Partners

Realizing turnkey embedded systems development.



## An Extended Arm Of Semiconductor And Systems Companies



**2100+**  
Expert Team

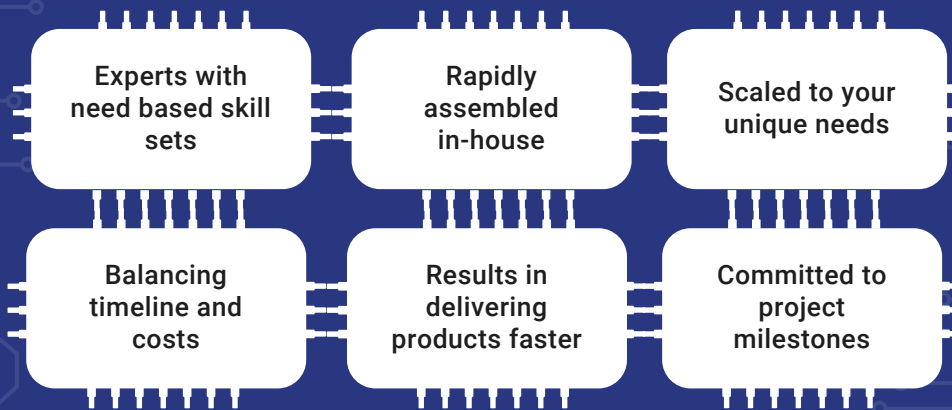


**Avg. 8+ Years**  
of experience with  
Critical Technologies



**90%**  
Technical Staff

# Building Your Project Team Customized To Your Needs



## Turnkey Facilities

Expertly Manned | Equipped | 24/7 Ready



ATE Test Lab



STPI SMART Lab



PCB Fab



FA & Reliability Lab



VLSI Design CoE

## The Outcome Speaks For Itself



900+ Test programs released



130 PCB designs per month



Verification IP (VIP) solution for different protocols & IPs



20+ Products Released to Market in various domain like Avionics/Automotive/ Industrial

India | USA | UK | Germany | Italy | Malaysia | Singapore  
China | Japan | South Korea



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